


- IC chips are usually covered with molded resin in the technical field of integrated circuit to which Coucoulas belongs. An opening is formed in a resin covering a lead frame by resin molding, and an outer electrical component is connected to the lead frame in the opening. Coucoulas fails to disclose or suggest this technique. Accordingly, it is not only inappropriate to combine the teachings of the two references, but it does not make sense technically to do so. Therefore, claim 1 is believed to be allowable.

Respectfully submitted,
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